

ABSTRACT

Semiconductor packages are provided. A semiconductor package includes a package base substrate that includes a base layer. A plurality of connection terminals are on the base layer. Moreover, a plurality of electromagnetic shielding terminals are on the base layer around the plurality of connection terminals. The semiconductor package includes a package body that includes at least one semiconductor chip. The semiconductor package includes an electromagnetic shielding layer on the package base substrate and on the package body.

FIG. 4A